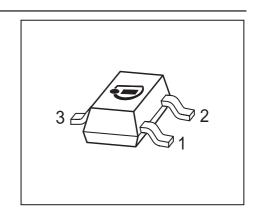


NPN Silicon RF Transistor

- For amplifier and oscillator applications in TV-tuners
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101







ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration			Package
BF517	LRs	1 = B	2 = E	3 = C	SOT23

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{\sf CEO}$	15	V
Collector-base voltage	V_{CBO}	25	
Emitter-base voltage	V_{EBO}	2.5	
Collector current	I _C	25	mA
Peak collector current	I _{CM}	50	
Total power dissipation ²⁾	P_{tot}	280	mW
_ <i>T</i> _S ≤ 55 °C			
Junction temperature	T_{i}	150	°C
Ambient temperature	T_{A}	-65 150	
Storage temperature	$T_{ m stg}$	-65 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ³⁾	R_{thJS}	≤ 340	K/W

¹Pb-containing package may be available upon special request

 $^{^2}T_{\mbox{\scriptsize S}}$ is measured on the collector lead at the soldering point to the pcb

 $^{^3}$ For calculation of R_{thJA} please refer to Application Note Thermal Resistance



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics	,			•	•
Collector-emitter breakdown voltage	V _{(BR)CEO}	15	-	-	V
$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$, ,				
Collector-base cutoff current	I _{CBO}				μΑ
$V_{CB} = 10 \text{ V}, I_{E} = 0$		-	-	0.05	
$V_{\rm CB} = 25 \text{ V}, I_{\rm E} = 0$		-	-	10	
Emitter-base cutoff current	l _{EBO}	-	-	100	
$V_{\text{EB}} = 2.5 \text{ V}, I_{\text{C}} = 0$					
DC current gain-	h _{FE}				-
$I_{\rm C}$ = 2 mA, $V_{\rm CE}$ = 1 V, pulse measured		40	-	150	
$I_{\rm C}$ = 25 mA, $V_{\rm CE}$ = 1 V, pulse measured		20	70	-	
Collector-emitter saturation voltage	V _{CEsat}	-	0.1	0.4	V
$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 1 \text{ mA}$					



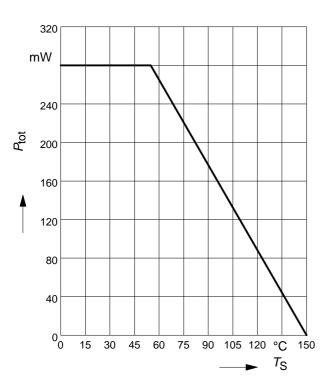
Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter Parameter State I A = 25° C, unle	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling	ng)				
Transition frequency	f_{T}				GHz
$I_{\rm C} = 2 \text{ mA}, \ V_{\rm CE} = 5 \text{ V}, \ f = 200 \text{ MHz}$		1	1.4	-	
$I_{\rm C} = 25 \text{ mA}, \ V_{\rm CE} = 5 \text{ V}, \ f = 200 \text{ MHz}$		1.3	2.5	-	
Collector-base capacitance	C _{cb}	-	0.55	0.8	pF
$V_{CB} = 5 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$,					
emitter grounded					
Collector emitter capacitance	C _{ce}	-	0.27	-	
$V_{CE} = 5 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$,					
base grounded					
Emitter-base capacitance	C _{eb}	-	0.9	1.45	
$V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{CB} = 0$,					
collector grounded					
Noise figure	F	-	3.5	5	dB
$I_{\rm C}$ = 2 mA, $V_{\rm CE}$ = 5 V, $Z_{\rm S}$ = 50 Ω ,					
f = 800 MHz					
Transducer gain	$ S_{21e} ^2$	-	13	-	dB
$I_{\rm C} = 20 \text{ mA}, \ V_{\rm CE} = 5 \text{ V}, \ Z_{\rm S} = Z_{\rm L} = 50 \Omega,$					
f = 500 MHz					
Third order intercept point at output	IP ₃	-	21.5	-	dBm
$V_{CE} = 5 \text{ V}, I_{C} = 20 \text{ mA}, f = 800 \text{ MHz},$					
$Z_{S} = Z_{Sopt}, Z_{L} = Z_{Lopt}$					
1dB Compression point	P _{-1dB}	-	10	-	-
$I_{\rm C} = 20 \text{ mA}, \ V_{\rm CE} = 5 \text{ V}, \ Z_{\rm S} = Z_{\rm L} = 50 \Omega,$					
f = 800 MHz					



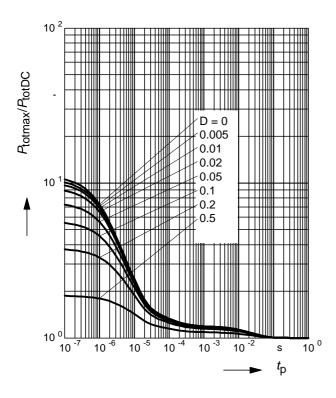
Total power dissipation $P_{tot} = f(T_S)$

Permissible Pulse Load $R_{thJS} = f(t_p)$



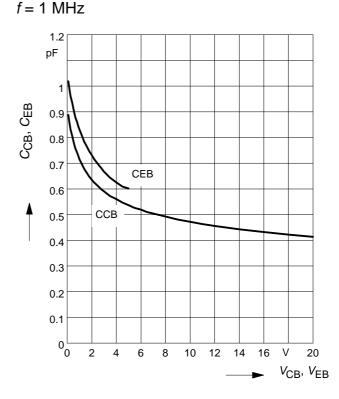
Permissible Pulse Load

$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_{p})$$



10³ K/W 10² 0.5 0.2 0.1 0.05 0.02 0.01 0.005 D = 0 10¹ 10⁻⁷ 10⁻⁶ 10⁻⁵ 10⁻⁴ 10⁻³ 10⁻² s 10⁰

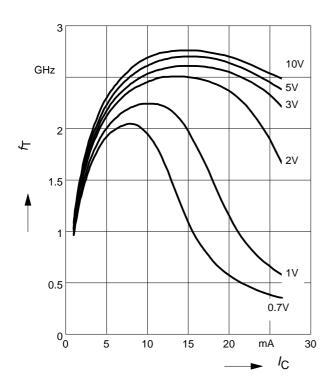
Collector-base capacitance $C_{cb} = f(V_{CB})$ Emitter-base capacitance $C_{eb} = f(V_{EB})$





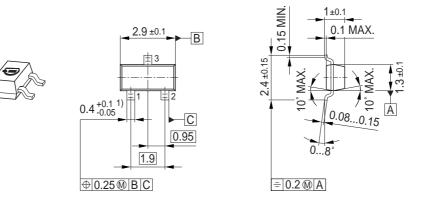
Transition frequency $f_T = f(I_C)$

 V_{CE} = parameter

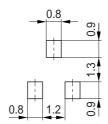




Package Outline

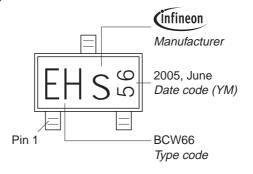


Foot Print



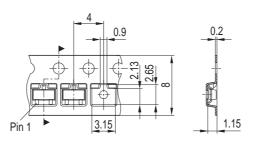
1) Lead width can be 0.6 max. in dambar area

Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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